



## Millimeter-Wave and Terahertz Technology

Guest Editors:

### **Dr. Houjun Sun**

Beijing Key Laboratory of  
Millimeter Wave and Terahertz  
Techniques, School of  
Information and Electronics,  
Beijing Institute of Technology,  
Beijing 100081, China

### **Dr. Hua Qin**

Key Laboratory of Nanodevices  
and Applications, Suzhou  
Institute of Nano-Tech and Nano-  
Bionics, Chinese Academy of  
Sciences, Suzhou 215123, China

### **Dr. Yu Xiao**

School of Electronics and  
Communication Engineering,  
Sun Yat-sen University,  
Guangzhou 510275, China

Deadline for manuscript  
submissions:

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### **Message from the Guest Editors**

The advances in silicon-based integration technology and the improvement of the HEMT process, with a higher machining accuracy and 2DEG density, make high-performance terahertz detection arrays and transceiver systems achievable, and enable a variety of interesting and valuable applications.

This Special Issue aims to demonstrate recent progress in detectors, antennas, and transceiver circuits based on silicon/HEMT/MEMS technologies, and on arrays for security imaging, non-destructive inspection applications, etc

- millimeter-wave and terahertz arrays for security imaging systems
- millimeter-wave and terahertz radar for industrial applications
- millimeter-wave and terahertz solid-state power amplifiers
- waveguide antenna array beyond W-band
- high-sensitivity terahertz receiving chains and systems





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## Editor-in-Chief

**Prof. Dr. Giulio Nicola Cerullo**

Dipartimento di Fisica,  
Politecnico di Milano, Piazza L.  
da Vinci 32, 20133 Milano, Italy

## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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Applied Sciences Editorial Office  
MDPI, St. Alban-Anlage 66  
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